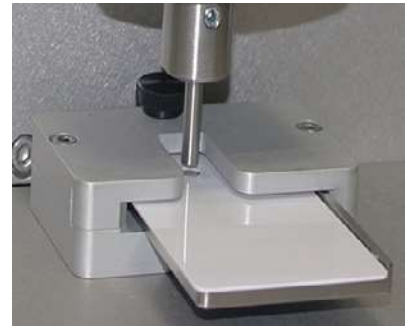




**OPTION**  
**Sim plug push**  
**Different tip shape**  
**Different diameter**



## Features & description

The ICM adhesion (back spot pressure) card testing equipment realises gluing resistance of chip.

- Stand-alone equipment with screen touch interface (30 programs memorized)
- Graphical return of the test session on the screen with maximum value
- Possibility to export data on a SD card
- Pressure: up to 250N
- Needs to realise a hole on the back of the card, made by BGI120C: Driller tool

## Advantages

- Tests for contact cards, dual cards, combi cards and customized cards
- Possibility to **test the cards further than the norm**

## Facilities / Environmental conditions

- Power: 100-240V AC
- Frequency: 50-60Hz single phase
- Power consumption: 200W maximum
- Operating temperature: +10°C to +40°C
- Dimensions: 350x330x730mm (WxDxH)
- Weight: 23kg

## Norms references

- CQM 2.22 : #3058#, #8230#

## Option: BGi120C - Driller tool



The driller tool is used to drill the back of the card before backside spot pressure test is performed on BGi175B.

- Stand alone and easy to use desktop equipment
- Tests for contact cards, dual cards, combi cards
- Safe tool compared to cutter
- Hole diameter: 6 mm or different with additional tools
- Dimensions: 230x400x380mm (WxDxH)
- Weight: 14kg